

# PATENT ASSIGNMENT

**SUBMISSION TYPE:** NEW ASSIGNMENT

**APPLICATION NUMBER**  
**10/065568**

**NATURE OF CONVEYANCE:** ASSIGNMENT OF ASSIGNOR'S INTEREST

## CONVEYING PARTY DATA

**Name:** Chen, Kuo-Ming

**Execution Date:** 10/16/2002

**Name:** Liu, Hung-Min

**Execution Date:** 10/16/2002

## RECEIVING PARTY DATA

**Name:** UNITED MICROELECTRONICS CORP.

**Street Address:** No.3, Li-Hsin Road 2

**Internal Address:** Science-Based Industrial Park

**City:** Hsin-Chu City

**State:**

**Country:** TAIWAN

**Postal Code:**

The USPTO, Office of Public Records, will send correspondence via facsimile to **FAX NUMBER:** +886-2-8923-7390

## CORRESPONDENCE DATA:

*Correspondence will be sent via US Mail when a fax number*

*has not been provided or the fax attempt is unsuccessful.*

When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.

**CUSTOMER NUMBER:** 027765

**NAME OF PERSON SIGNING:** WINSTON HSU

**DATE SIGNED:** 10/31/2002

**Total Attachments:** 2

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNORS (Inventors):**

Name: Kuo-Ming Chen Nationality: R.O.C.

Address: No. 16-1, Ta-Lin Tsun, Pei-Pu Hsiang, Hsin-Chu Hsien, Taiwan, R.O.C.

Name: Hung-Min Liu Nationality: R.O.C.

Address: 4F, No. 30, Lane 81, Ta-Hsueh Rd., Hsin-Chu City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to **UNITED MICROELECTRONICS CORP.**  
(hereinafter 'Assignee'), of (Assignee address)  
**No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C.**  
, and the successors assigns and legal representatives of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"**SOLDER BUMP STRUCTURE AND LASER REPAIR PROCESS FOR MEMORY DEVICE**"

Which is found in :

- (a) \_\_\_\_\_ U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

and, in and to, all Letters Patent to be obtained for said invention by the above application or ant continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this 10/16/2002 (Date of signing).

(Type name of inventor)

**Signature of INVENTOR**

Kuo-Ming Chen

Kuo-ming Chen

Hung-Min Liu

Hung-Min Liu